

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5908824

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chin-Chun Huang	01/10/2020
Yun-Pin Teng	01/10/2020
JINJIAN OUYANG	01/10/2020
WEN YI TAN	01/10/2020
RECEIVING PARTY DATA	
Name:	United Semiconductor (Xiamen) Co., Ltd.
Street Address:	NO.899 Wan Jia Chun Road, Xiamen Xiang'an
City:	Xiamen, Fujian
State/Country:	CHINA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16741698
CORRESPONDENCE DATA	
Fax Number:	(703)997-4517
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	3027291562
Email:	Patent.admin.uspto.cr@naipo.com
Correspondent Name:	WINSTON HSU
Address Line 1:	5F., NO.389, FUHE RD., YONGHE DIST.,
Address Line 4:	NEW TAIPEI CITY, TAIWAN
ATTORNEY DOCKET NUMBER:	NAUP3548USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	01/13/2020
Total Attachments: 8	
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**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Title of Invention:

RRAM STRUCTURE AND METHOD OF FABRICATING THE SAME

As the below named inventor, I hereby declare that:
This declaration is directed to:

- The attached application, or
- United States application number _____ filed on _____, or
- PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **United Semiconductor (Xiamen) Co., Ltd.** having a postal address of _____

NO.899 Wan Jia Chun Road, Xiamen Xiang'an, Xiamen, Fujian 361100, P.R.C.

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.
IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chin-Chun Huang**

Date: **JAN 10 2020**

Signature: Chin-Chun Huang

RECEIVED
JAN 10 2020
USPTO

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Yun-Pin Teng

Date: JAN 10 2020

Signature: Yun - Pin Teng

U.S. PATENT AND TRADEMARK OFFICE

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: JINJIAN OUYANG

Date: JAN 10 2020

Signature: JIN JIAN OUYANG

[Faint, diagonal watermark or bleed-through text, possibly containing the name 'JIN JIAN OUYANG']

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: WEN YI TAN

Date: JAN 10 2020

Signature: 

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JAN 13 2020
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